



MARK



修改管脚



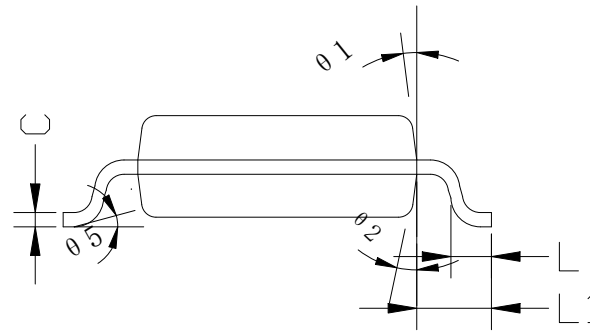
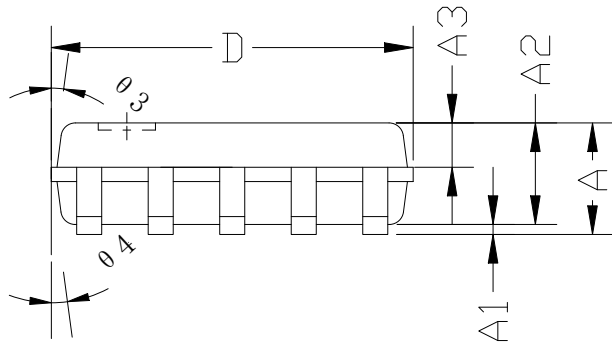
修改b、b1

REVISION RECORD

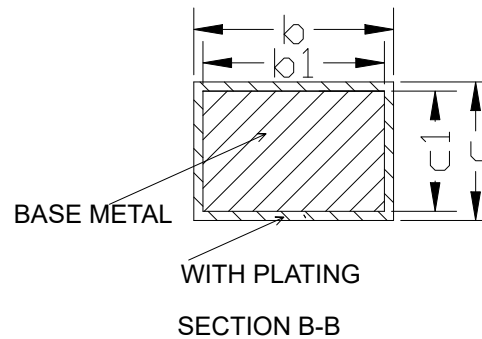
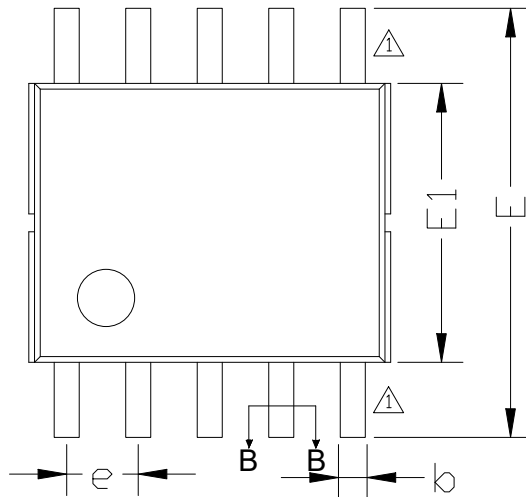
VERSION

B

REVISERE



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	1.65
A1	0.10	--	0.25
A2	1.40	1.42	1.50
A3	0.57	0.62	0.67
b	0.33	--	0.41
b1	0.32	0.35	0.38
c	0.20	--	0.24
c1	0.19	0.20	0.21
D	4.80	4.90	5.00
E	5.90	6.00	6.20
E1	3.85	3.90	4.00
e	1.00<BSC>		
L	0.50	0.60	0.70
L1	1.05<BSC>		
theta 1	6°	~	12°
theta 2	6°	~	12°
theta 3	5°	~	10°
theta 4	5°	~	10°
theta 5	0°	~	6°



BASE METAL

WITH PLATING

SECTION B-B

技术说明:

- 1) LEADFRAME MATERIAL: COPPER;  
引线框架材料: 铜;
- 2) LEADFRAME THICKNESS: 0.203mm;  
引线框架厚度: 0.203mm;
- 3) BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;  
塑封体长度及宽度尺寸不包括塑封溢胶;
- 4) REFERENCE: JEDEC MS-013, MS-012.  
参考标准: JEDEC MS-013, MS-012.

SCALE	UNIT	mm	TITLE
DATE	2025-01-14		SSOP10L 产品成型图
DESIGNER	CHECKER	APPROVER	
张金萍			DWG.NO. MT-PD-100
2024-01-14			VERSION C 第1页 共1页